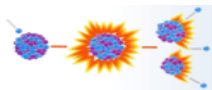




## Electrochemical and thermal synthesis of $\text{Nb}_3\text{Sn}$ coatings on Nb substrates

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Qingwei Chu, Teng Tan, IMP, CAS  
2021-03-16



## 1. Background

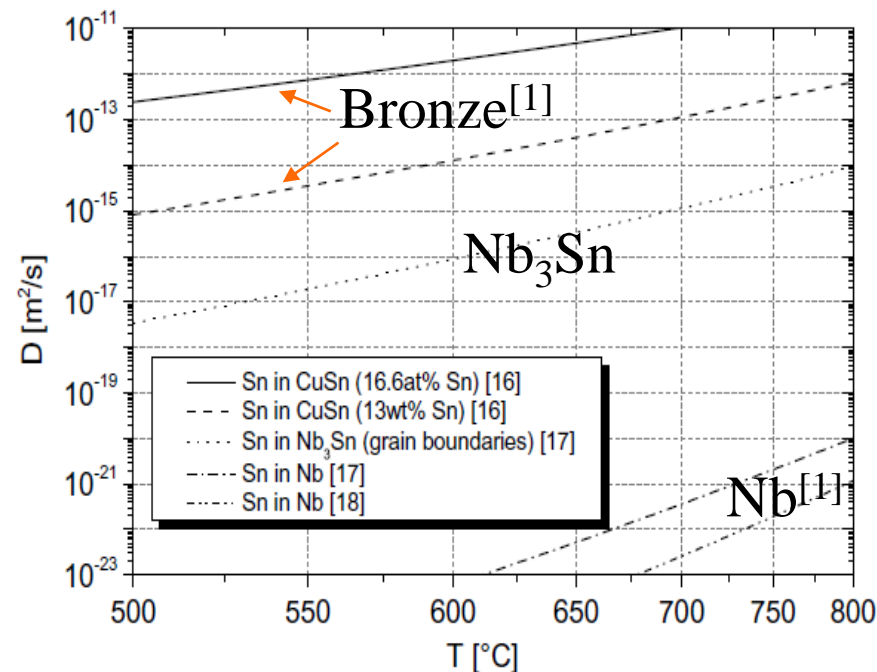
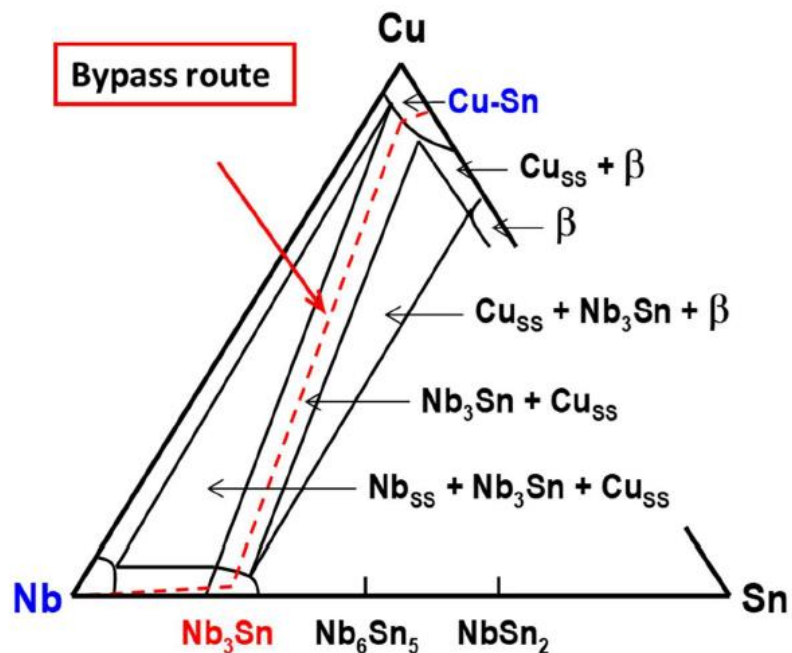
## 2. Nb<sub>3</sub>Sn thin film activities

- Route 1: Nb/Cu/Sn/Cu multilayer films
- Route 2: Nb/Bronze layer films
- Route 3: Cu/Nb/Bronze multilayer films

## 3. Conclusion

# Background: $\text{Nb}_3\text{Sn}$ bronze process

Phase diagram of Nb-Cu-Sn ternary system [2] at 700°C

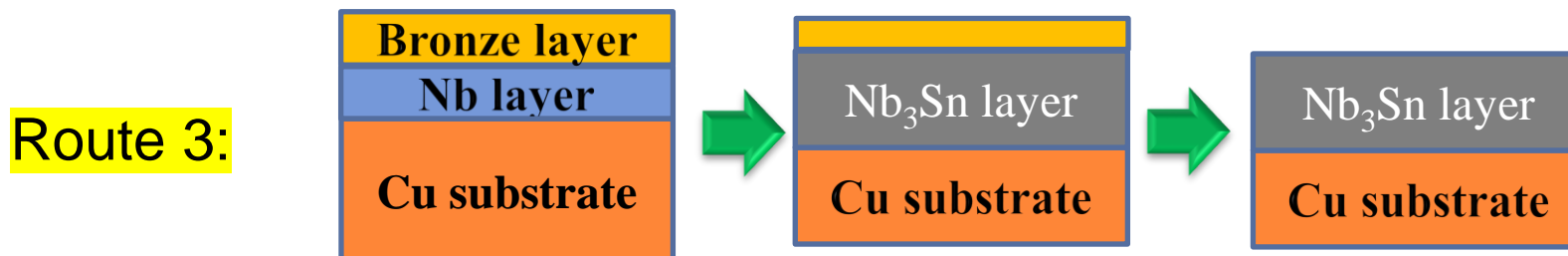
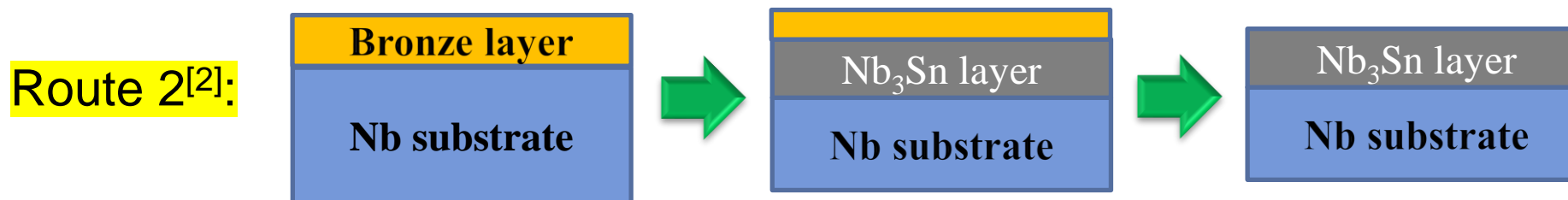
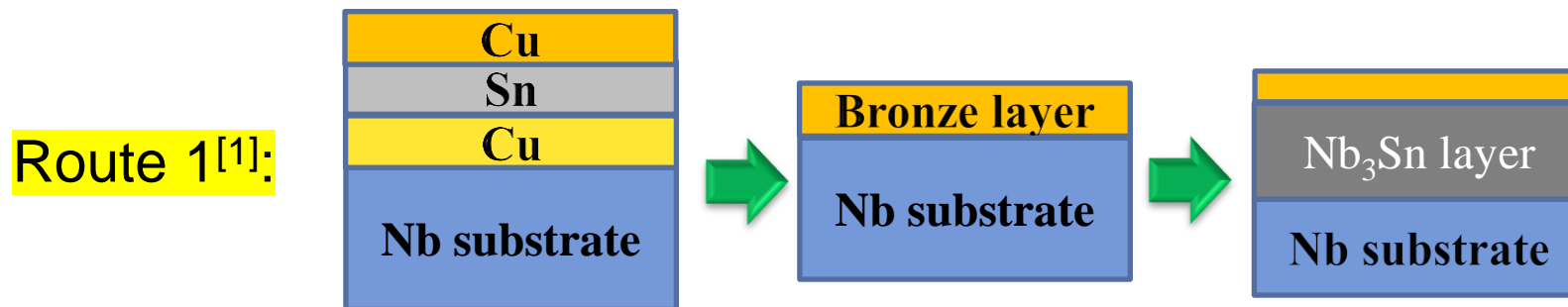


1. The copper can facilitate the interdiffusion between Nb and Sn by 7~10 magnitudes of orders.
2. The copper alloy will be excluded from the  $\text{Nb}_3\text{Sn}$  phase by itself.

[1] H. Müller and T. Schneider, "Heat treatment of  $\text{Nb}_3\text{Sn}$  conductors," Cryogenics, vol. 48, pp. 323-330, 2008/07/01/ 2008.

[2] L Mei, Z Du, C Guo, & C Li. (2009). Thermodynamic optimization of the cu-sn and cu-nb-sn systems. Journal of Alloys & Compounds, 477(1-2), 104-117.

# Background: Nb<sub>3</sub>Sn bronze process



[1] E. Barzi, M. Bestetti, F. Reginato, D. Turrioni, S. Franz, Synthesis of superconducting Nb<sub>3</sub>Sn coatings on Nb substrates, Superconductor Science and Technology 29 (2016) 015009.

[2] M. Lu, F. Pan, H. Guo, S. Huang, Z. Yang, Q. Chu, F. Liu, T. Tan, Electrochemical and thermal synthesis of Nb<sub>3</sub>Sn coatings on Nb substrates, Materials Letters 292 (2021) 129557.

## Roughness reduction

- Sand paper grinding and polishing



## Degreasing

- 1%~2% micro-90®
- Ultrasonic cleaning
- 20 minutes



## Removal of oxide (EP)

sulphuric acid :  
hydrofluoric  
acid about 9:1  
10 minutes

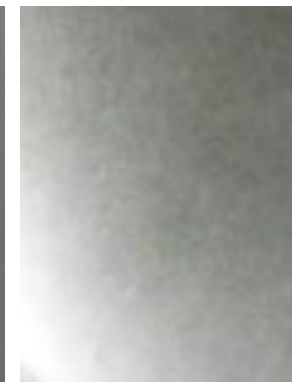


## Surface activation

- 10% dilute sulfuric acid
- Wash with deionized water

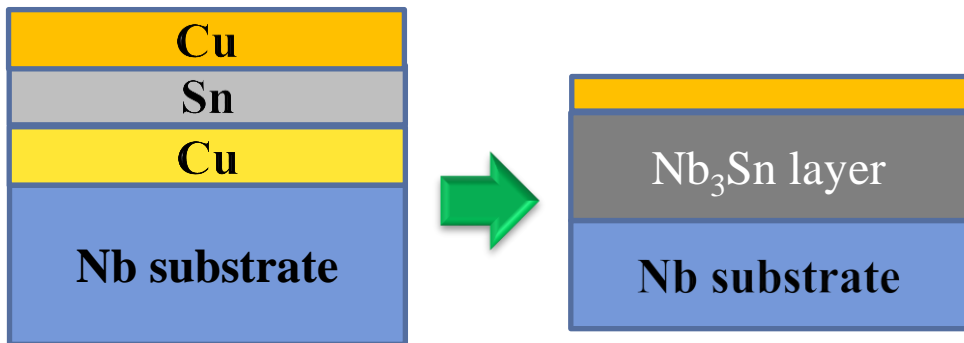


Before EP

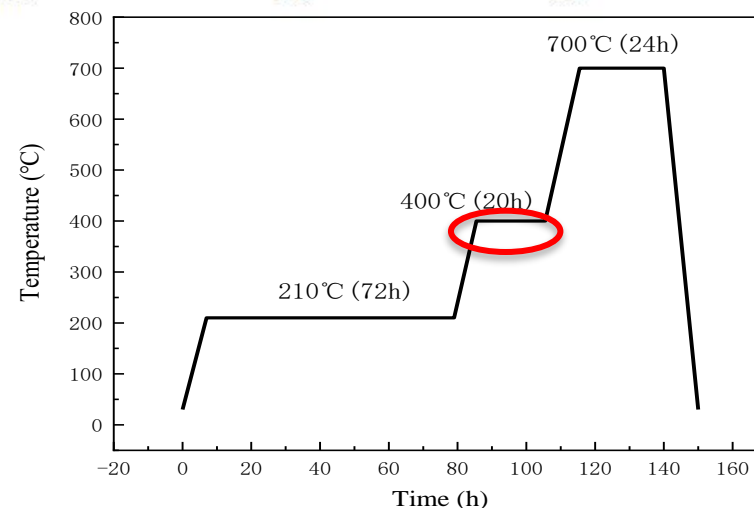
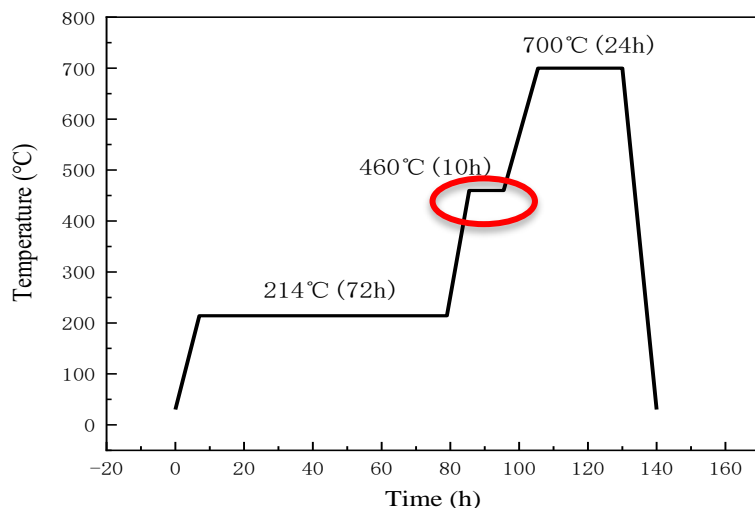


After EP

# Route 1: Nb/Cu/Sn/Cu multilayer films



Nb                      Cu                      Sn                      Cu                      annealing

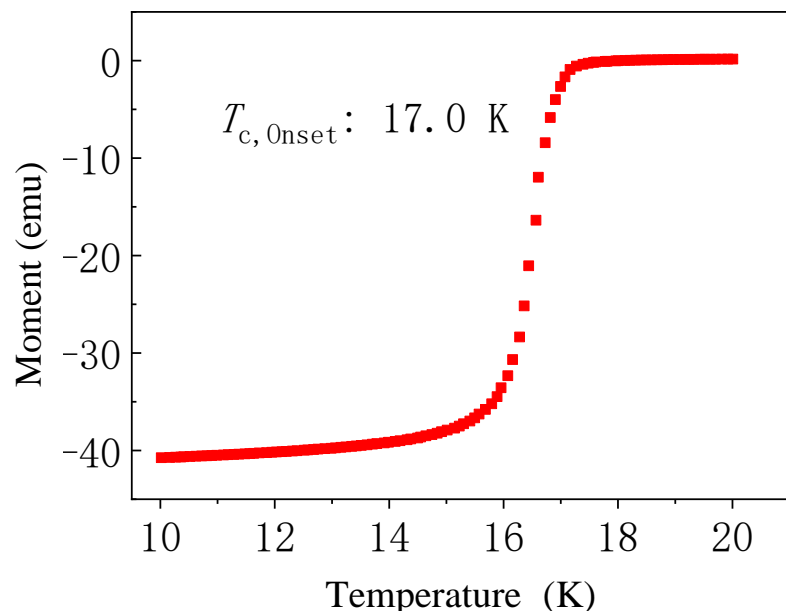


210°C(72h):Relieve the stress, give off water vapor and form copper-tin alloy

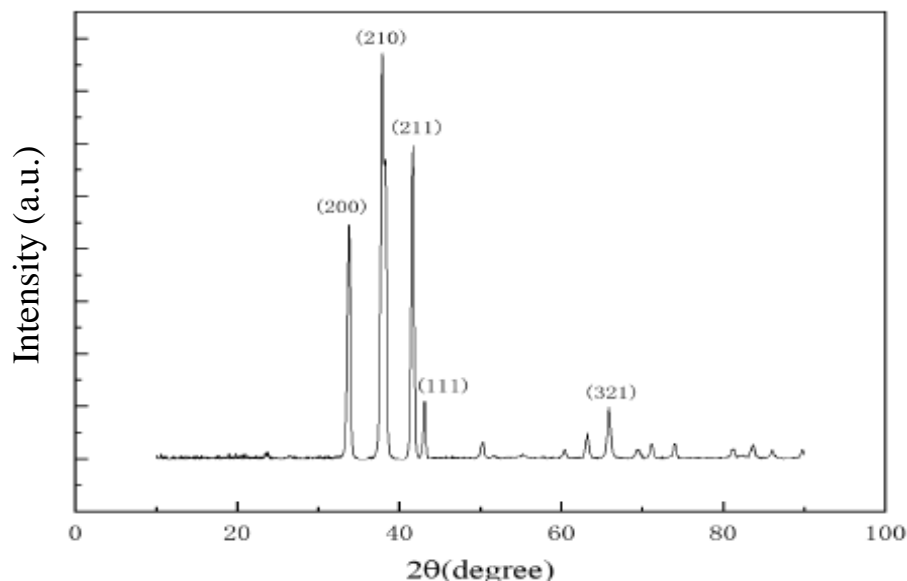
400°C(20h):Reduce the number of Kirkendall hole and increase grain size by extending medium treatment time

700°C(24h):Form the Nb<sub>3</sub>Sn superconducting phase

## Superconducting properties:



M-T measurements showed  $T_c$  17.0K



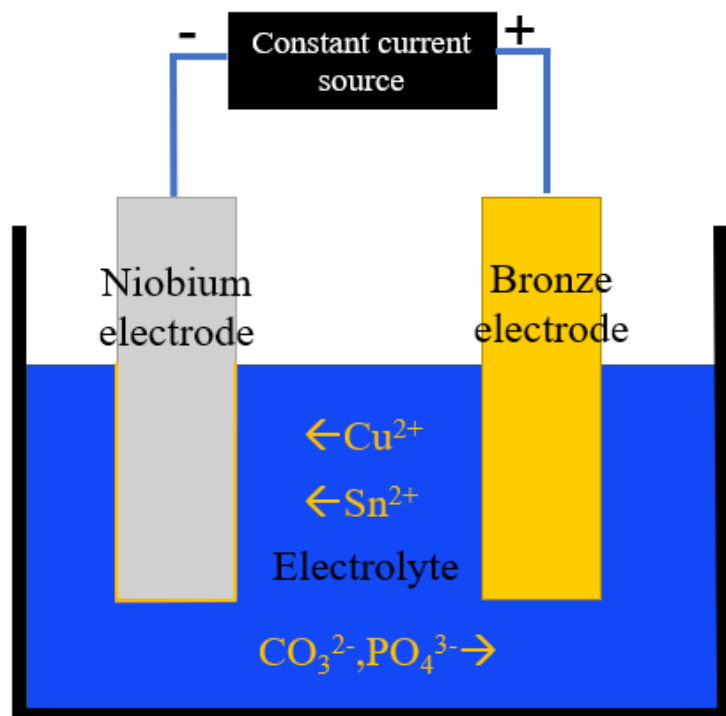
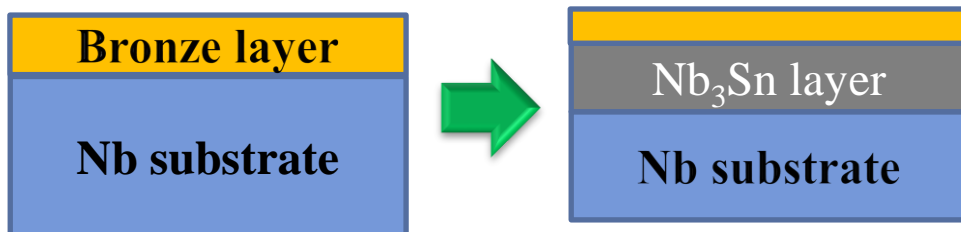
XRD patterns showed the formation of  $\text{Nb}_3\text{Sn}$  phase

## Problems:

1. Films are easily broken, peel off or cracked.
2. Bubbles appear in the film after heat treatment.
3. There are copper, tin and other impurity phases in  $\text{Nb}_3\text{Sn}$  films.



# Route 2: Nb/Bronze layer films



Schematic diagram of Cu-Sn co-deposition



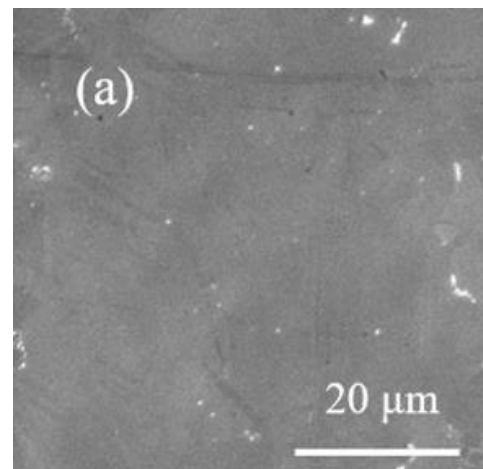
Nb



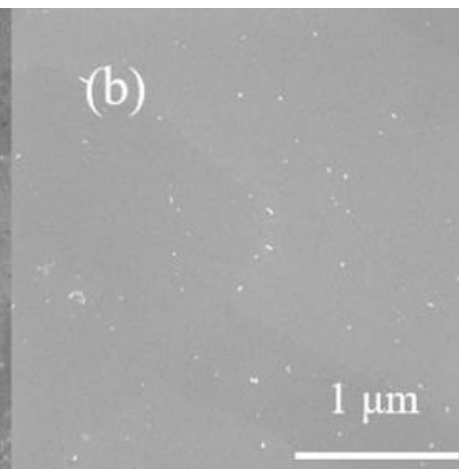
Nb/Bronze



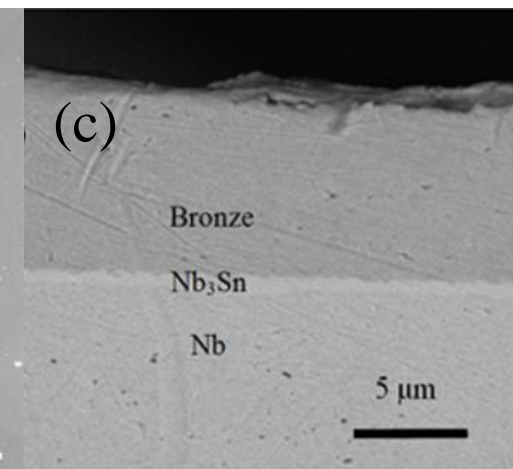
Nb/Nb<sub>3</sub>Sn/Cu



(a)



(b)

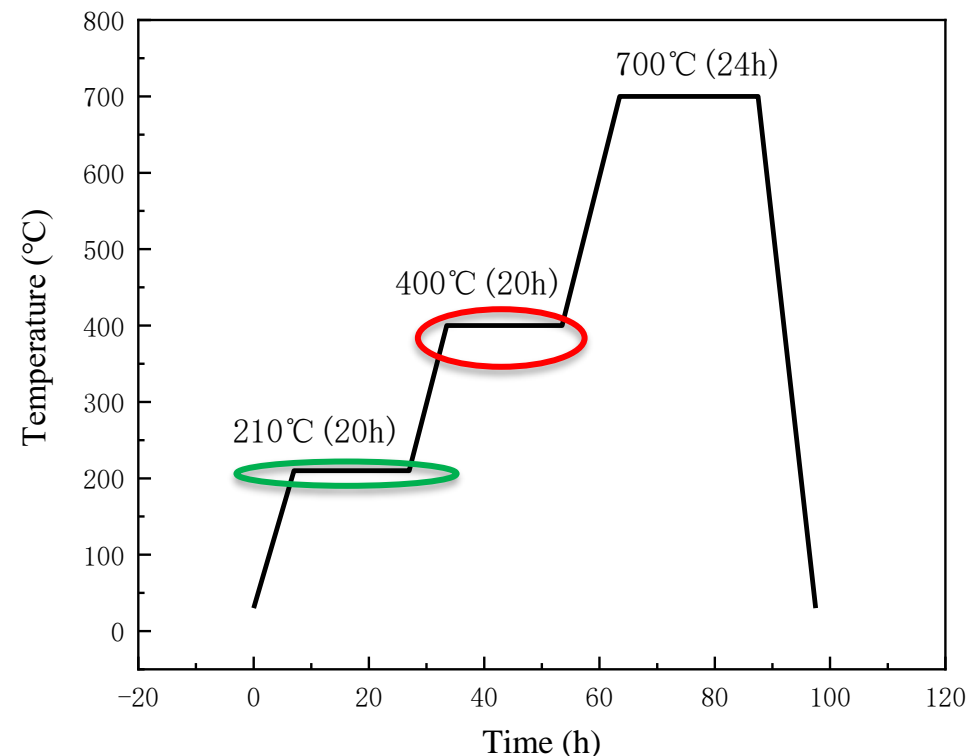
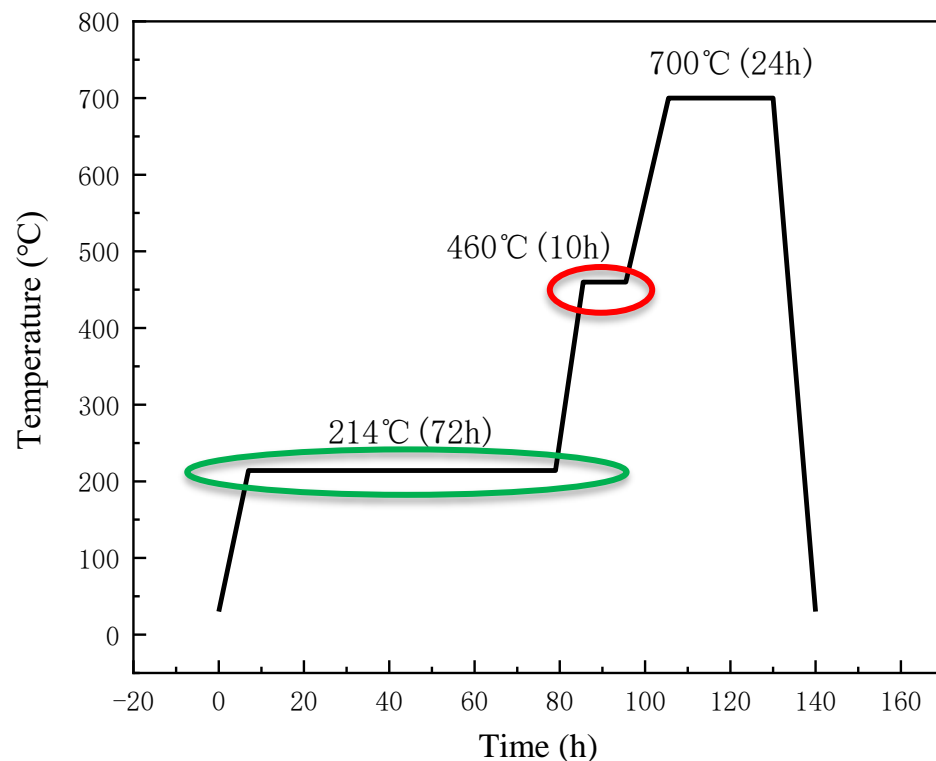


(c)

Bronze  
Nb<sub>3</sub>Sn  
Nb

SEM picture of sample surface (a, b) before electropolishing under different magnification.



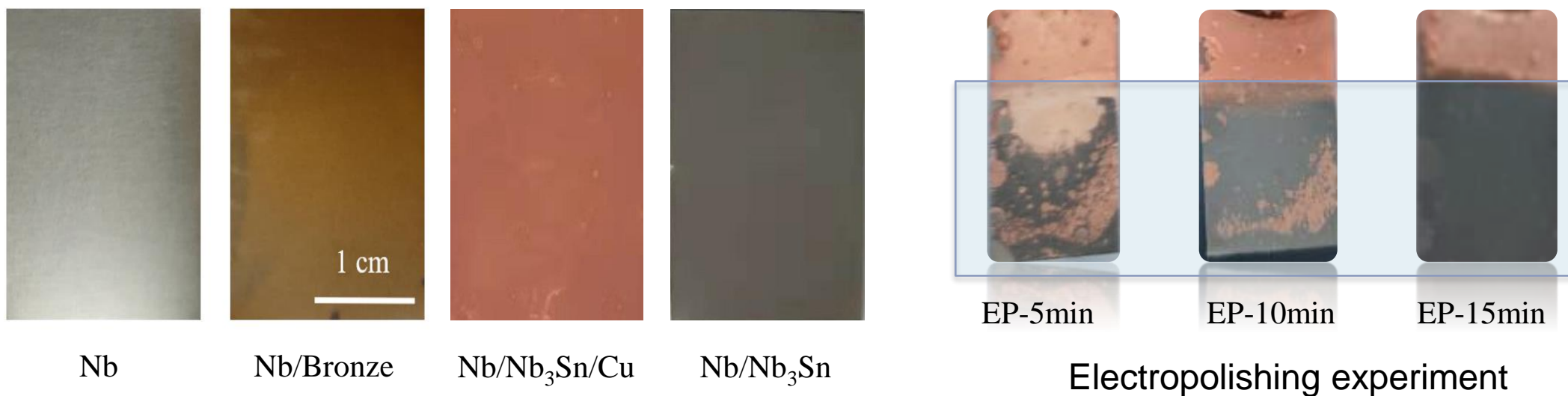


210°C(20h): The treatment time of low temperature bronzing is greatly reduced

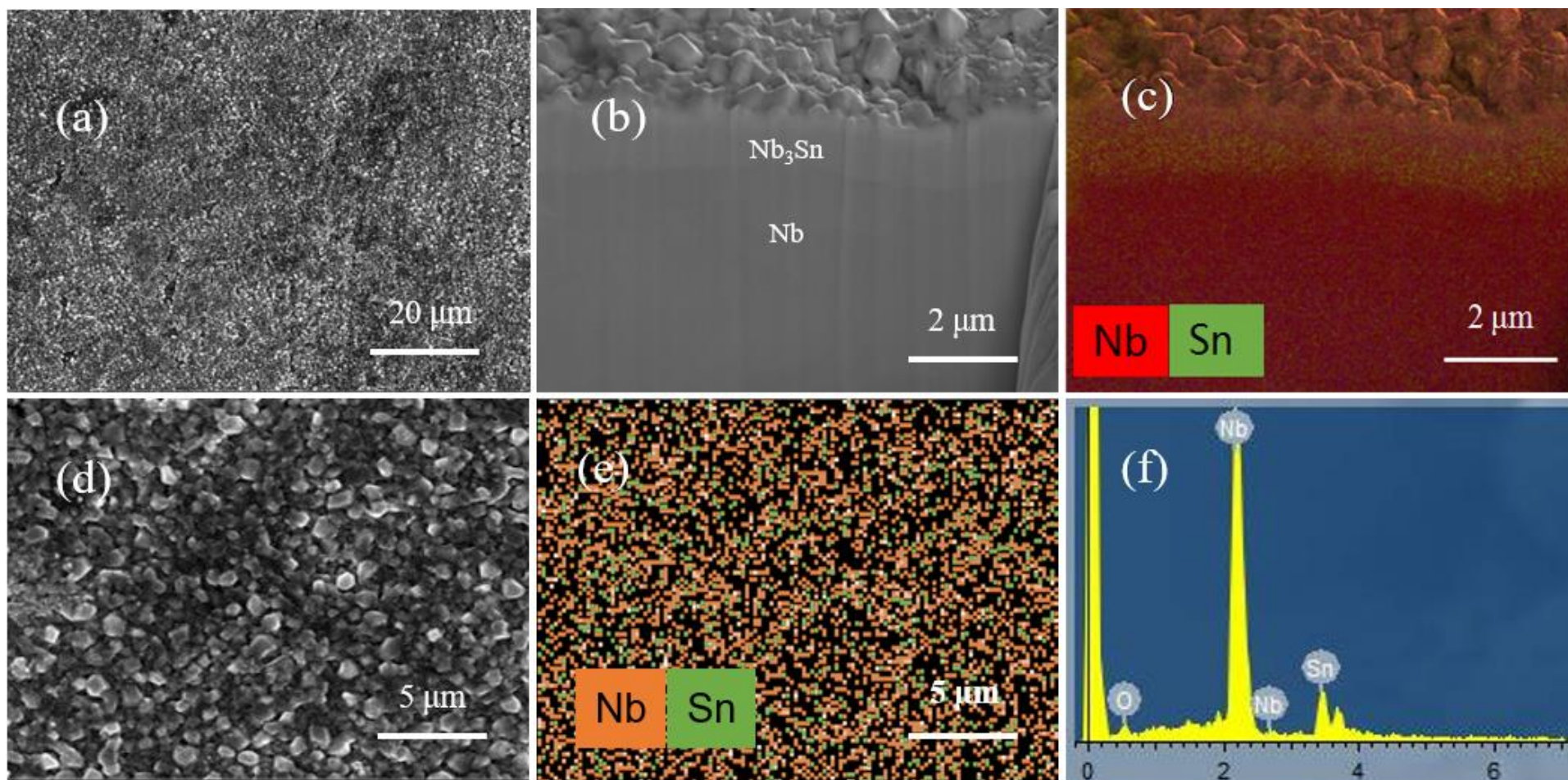
400°C(20h): Reducing the number of Kirkendall hole and increase grain size by extending medium treatment time

700°C(24h): The formation of  $\text{Nb}_3\text{Sn}$  superconducting phase

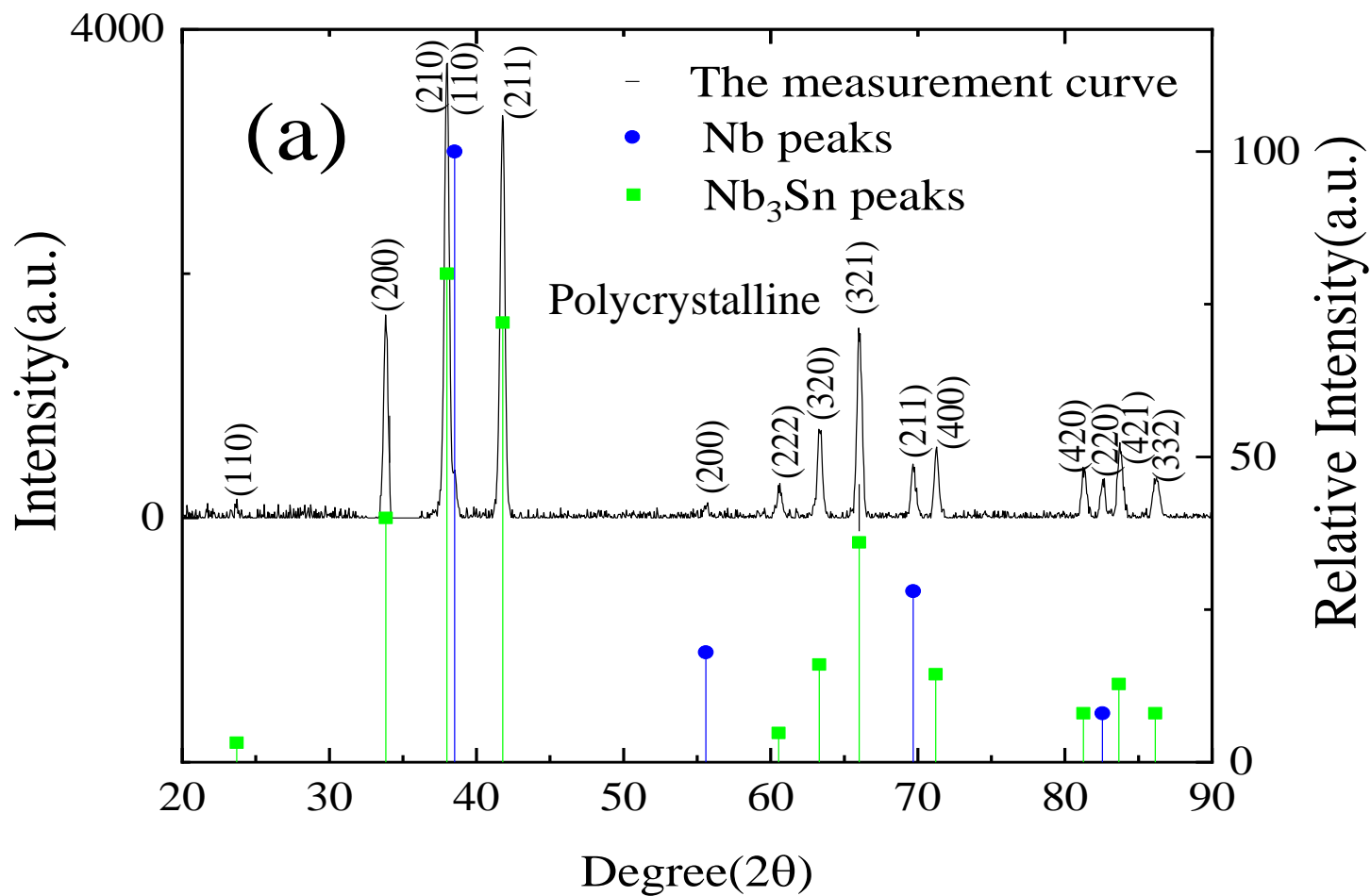
# Route 2: Removing bronze layer



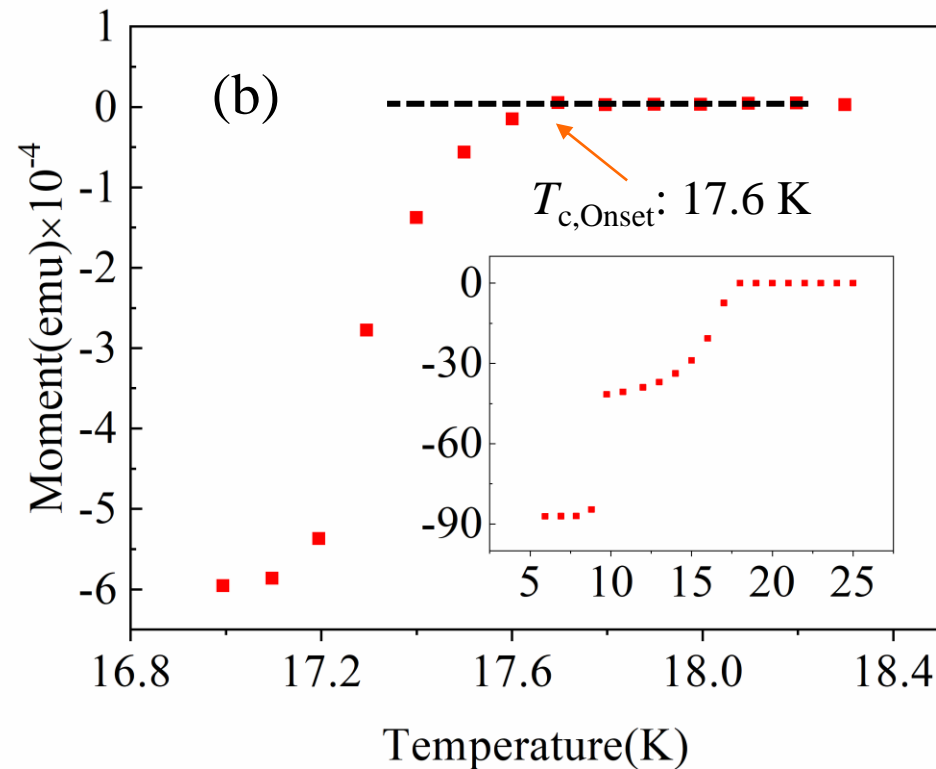
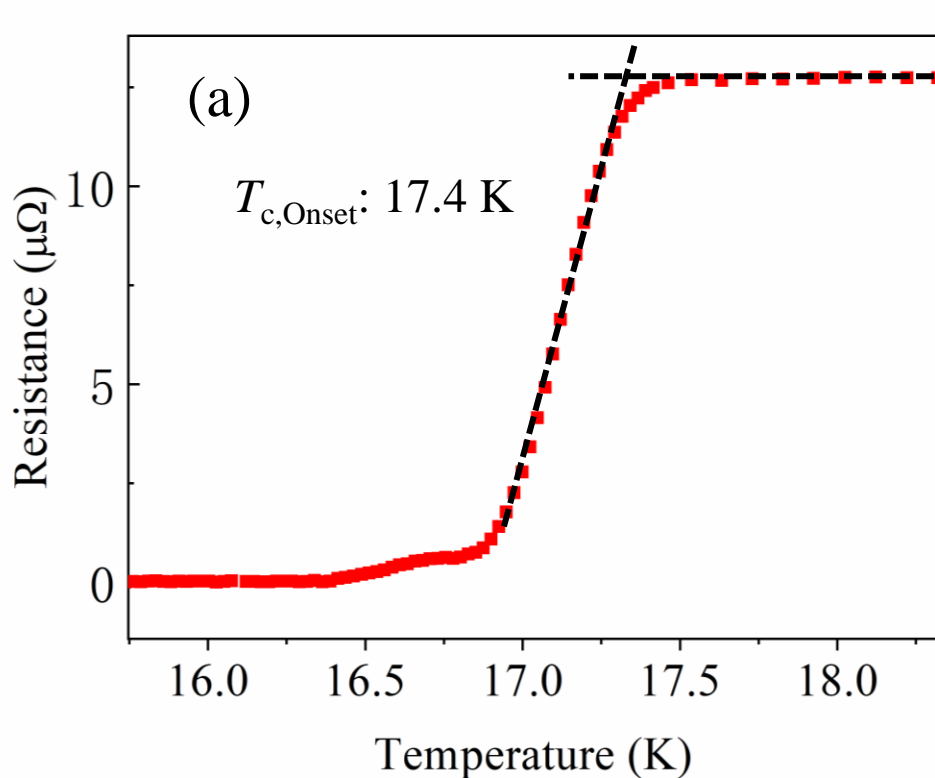
1. Phosphoric acid and ethylene glycol mixed in a volume ratio of 3:2
2. The electropolishing of surface bronze layer was performed at a current density of 50 mA/cm<sup>2</sup> and bath temperature of 25°C. Polishing time is about 15 minutes



Morphology and Composition: Sample (a) surface and (b) cross-section SEM pictures after electropolishing, (c) the elemental mapping. The top-view SEM picture (d) morphology, (e) the elemental mapping, and (f) the EDX analysis of surface after electropolishing.

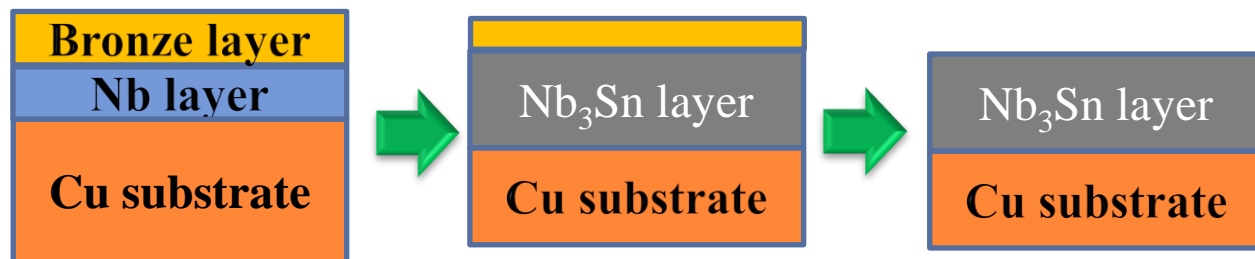


The XRD pattern of sample consisting of Nb/Nb<sub>3</sub>Sn surface.



DC electrical measurement (a) of critical temperature  $T_c$ , and DC magnetic measurement (b) of critical temperature  $T_c$





Removal of bronze layer by electropolishing after annealing  
Nb: magnetron sputtering



Cu/Nb



Cu/Nb<sub>3</sub>Sn/Bronze



Cu/Nb<sub>3</sub>Sn

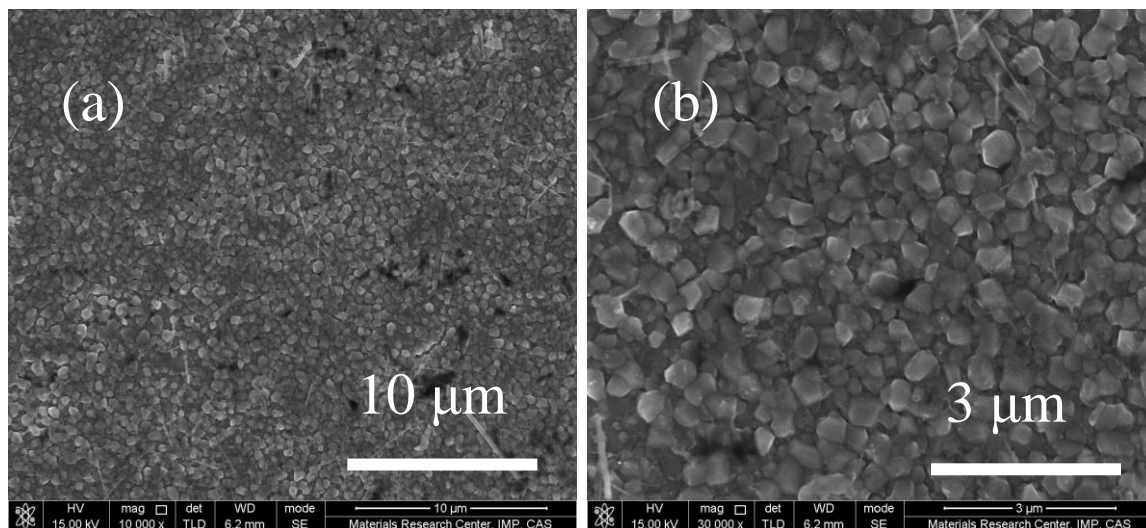


Early attempts: cracks

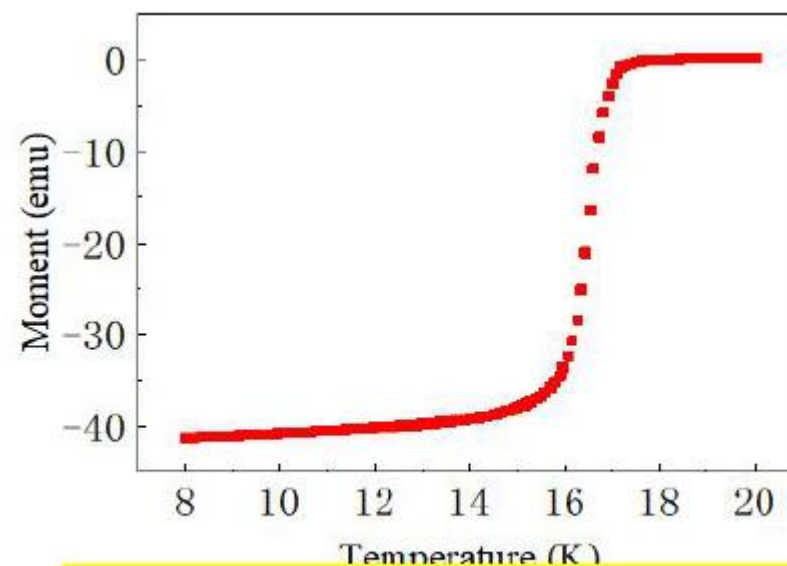


Early attempts: cracks

Sample properties:



SEM picture of sample surface (a, b) before electropolishing under different magnification.



M-T measurement show  $T_{c, \text{Onset}} \sim 17\text{K}$

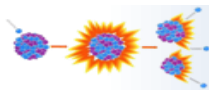






A combined electrochemical-thermal synthesis (ETS) technique of  $\text{Nb}_3\text{Sn}$  film on Nb substrates was presented.

- The medium temperature treatment technology has been improved.
- Direct bronze alloy precursor can avoid a long process of copper and tin alloying, requiring only a short period of low temperature pre-treatment to remove moisture, residual gas and stress. High quality  $\text{Nb}_3\text{Sn}$  film on Nb substrate can be obtained. The highest  $T_c$  observed on these samples was 17.6 K.
- After heat treatment, the residual copper and bronze layer on top of the sample could be completely removed by electropolishing.
- Its low temperature annealing allows the fabrication of  $\text{Nb}_3\text{Sn}$  thin film on copper cavity.



**Thanks for your attention.**